

## 有铅

Sn50/Pb50 SnPbBi

1 0.4mm

2 12

3

4

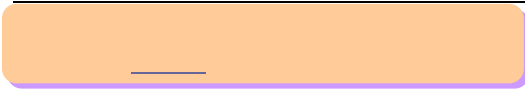
5 “ --- ” “ ”

6 PCB

7 ICT

8 Paste in hole

		ROL1	J-STD-004
		0.2wt%	
(SIR)		$1 \times 10^{13}$	25mil
		$1 \times 10^{12}$	40 90%RH 96Hrs
		$1 \times 10^5$	
			IPC-TM-650
			IPC-TM-650
			In house
		85~91wt% ± 0.5	
		9~15wt% ± 0.5	
		200 Pa.s ± 10% Malcolm (10rpm, 25 )	T3, 90% metal for printing
		80 Pa.s ± 10% Malcolm (10rpm, 25 )	T4, 87% metal for syringe
		0.55 ± 0.05	In house
		90%	Copper plate (Sn63, 90% metal)
			J-STD-005
			In house
Vs		48gF 0	IPC-TM-650 ± 5%
		56gF 2	
		68gF 4	
		44gF 8	
		12	In house
			0~10



**1**

T3 mesh -325/+500 25~45μ m

Fine pitch

**2**

1) “ ”

0~10

200

4

2) “ ”

3

1 ;

(适当的搅拌时间因搅拌方式、装置及环境温度等因素而有所不同，应在事前多做试验来确定)。

**3**



有铅免洗

0.4mm

0.12mm



有铅免洗

80%

	60 ~ 90HS
	45 <sup>0</sup> ~ 60 <sup>0</sup>
	2 ~ 4 × 10 <sup>5</sup> pa
	20 ~ 40mm/sec 15 ~ 20mm/sec 50 ~ 100mm/sec
	25 ± 3 40 ~ 70%



\*

\*

\*

PCB

PCB

A5

200g

B5

300g

A4

400g

4

4

5

6

此有铅



500g

PE

20

35



0 ~10

•

•

0

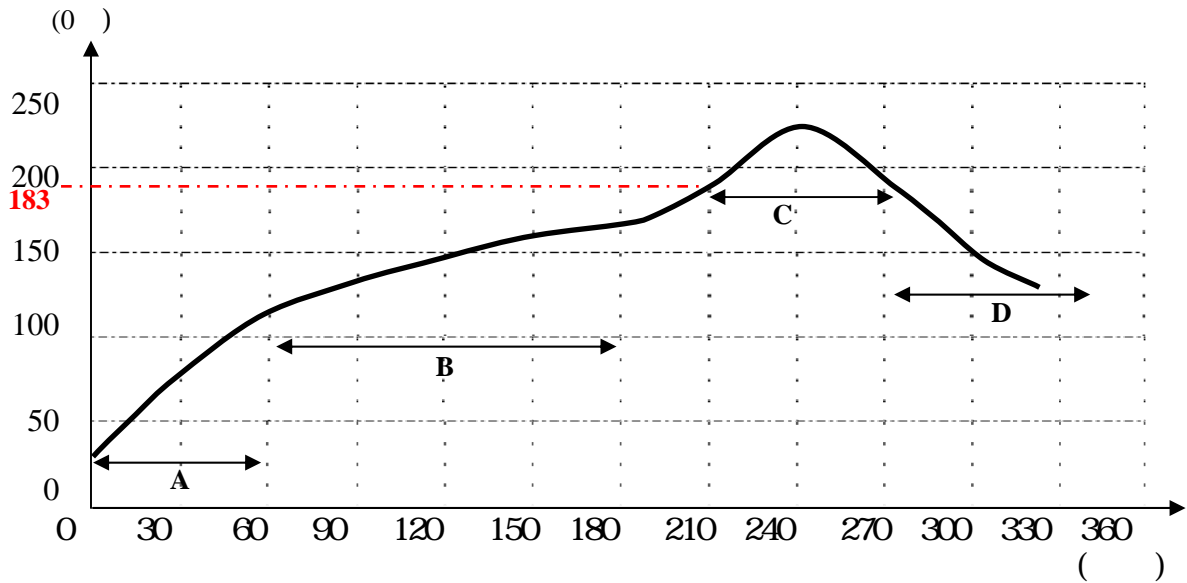
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MSDS

## 有铅

Sn50/Pb50 SnPbBi



A. \_\_\_\_\_ 25~33%

\* 1.0~3.0 /  
\*

B. \_\_\_\_\_ 33~50%

\* 150~200          60~90          PCB          1.5 /

C. \_\_\_\_\_

\* 230~245          183          70~90          Important          200          50~65  
\*  
\*

D. \_\_\_\_\_

\* 4          75  
\*  
\*

➤  
➤  
➤

“        ”          “        ”